

In the claims:

Please substitute the following full listing of claims for the claims as originally filed or most recently amended.

1. (Currently Amended) An integrated circuit including
a patterned copper layer,
a patterned aluminum layer,
a stud connection in an opening in a layer of material between a location on said patterned copper layer and a location on said patterned aluminum layer, said stud connection being formed of tungsten, and
a liner in said opening and having a thickness extending between said stud connection and said copper layer at said location on said patterned copper layer.
2. (Original) An integrated circuit as recited in claim 1 wherein said liner comprises
a layer of tantalum nitride, and
a layer of PVD tungsten.
3. (Original) An integrated circuit as recited in claim 1 wherein said liner comprises
a layer of titanium, and
a layer of titanium nitride or PVD tungsten.
4. (Cancelled)
5. (Original) An integrated circuit as recited in claim 1 wherein said patterned aluminum layer includes a layer of at least one of titanium and titanium nitride.
6. (Original) An integrated circuit as recited in claim 2 wherein said patterned aluminum layer includes a layer of at least one of titanium and titanium nitride.

C2

7. (original) An integrated circuit as recited in claim 3 wherein said patterned aluminum layer includes a layer of at least one of titanium and titanium nitride.

8. (Cancelled)

9. (Original) An integrated circuit as recited in claim 1, further including a covering layer.

10. (Original) An integrated circuit as recited in claim 9 wherein said covering layer includes a layer of silane-based high density plasma oxide.

11. - 16. (Withdrawn)

C2
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